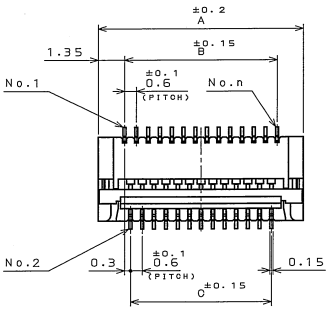
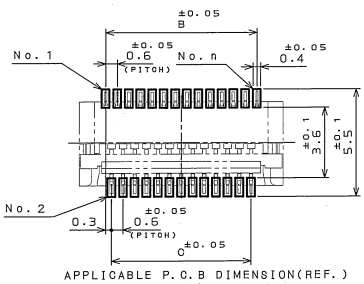
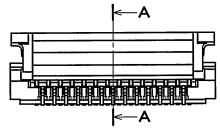
図面番号(DRAWING NO.) SJ035758

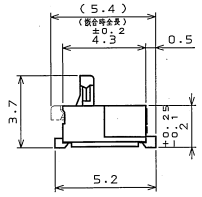
版数 REV.	年月日 DATE	DCN NO.	変更内容 DESCRIPTION	製図 DR.	担当 CHK.	査閲 APPD.	承認 APPD.
2	30.Mar.2001	47908	ADDED ITEM		N.IKENAGA	———	H.AMEMIYA
3	28.Mar.2002	49750	ADDED ITEM		N.IKENAGA	M.SUZUKI	T.MORINO
4	14.May.2002	49942	ADDED ITEM		N.IKENAGA	M.SUZUKI	T.MORINO
5	2.Dec.2003	053895	ADDED ITEM		N.IKENAGA	—	Y.Ichijima

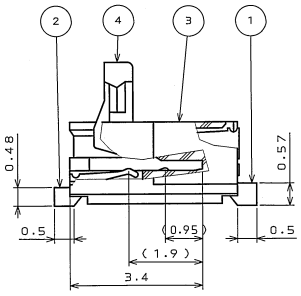




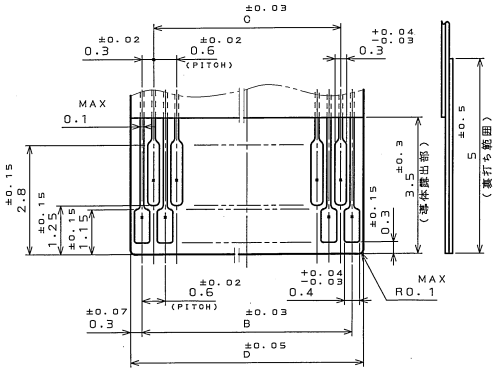
APPLICABLE P.C.B DIMENSION(REF.)
適合基板寸法(参考)







SECT. A-A
(SCALE 10:1)



(NOTE1)
APPLICABLE F.P.C DIMENSION(REF.)
適合FPC寸法(参考)
(THICKNESS:0.2±0.03)

NOTE1.POLYIMIDE SHOULD BE USED AS A REINFORCED BOARD AND THERMOSETTING ADHESIVE SHOULD BE USED.
BARE TRACES SHOULD BE GIVEN GOLD PLATING.

注1.適合FPCの補強板はポリイミドを使用し、接着剤は熱硬化性を使用すること。
又、仕上げは金メッキのこと。

TABLE 1

	NO. OF CONTACT	A	B	C	D
	17	7.5	4.8	4.2	5.4
△	21	8.7	6	5.4	6.6
△	25	9.9	7.2	6.6	7.8
△	27	10.5	7.8	7.2	8.4
	33	12.3	9.6	9.0	10.2
△	39	14.1	11.4	10.8	12
△	45	15.9	13.2	12.6	13.8
△	51	17.7	15	14.4	15.6
△	57	19.5	16.8	16.2	17.4

NO.	名称 DESCRIPTION	個数 QTY.	材料 MATERIAL	仕上 FINISH	備考 REMARKS
4	SLIDER	1	GLASS FILLED PPS		COLOR:BROWN UL94V-0
3	BASE INSULATOR	1	GLASS FILLED LCP		COLOR:BEIGE UL94V-0
2	CONTACT 2	n−1 / 2	COPPER ALLOY	SELECTIVE GOLD PLATING	
1	CONTACT 1	n+1 / 2	COPPER ALLOY	GOLD PLATING	

仕様書(SPECIFICATION)	JAOS-1656 JAHL-1656	第1版(ORIGINAL DATE)	14.Feb.2001
一般公差(GENERAL TOLERANCE)		製図 DR.	
寸法(DIMENSION)	角度(ANGLES)	担当 CHK.	N.IKENAGA
. ±0.8	X° ±	査閲 APPD.	———
.X ±0.4	X°X'±	承認 APPD.	H.AMEMIYA
.XX ±0.1			
.XXX±			

尺度(SCALE) 5:1 | 投影法(PROJECTION) FIRST ANGLE

名称(TITLE) IL-FHJ-**S-HF-N1

重量(WEIGHT)

日本航空電子工業株式会社
JAPAN AVIATION ELECTRONICS INDUSTRY, LTD.

図面番号(DRAWING NO.) SJ035758

版数(REV.) 5

SIZE A3

ODS-01-180-50065

DOF-0-212D(98.02)

JAE-CONNECTOR.COM
Reference Only

JAE CONNECTOR DIV. PROPRIETARY.
COPYRIGHT(C) 2001, JAPAN AVIATION ELECTRONICS INDUSTRY, LTD.

Downloaded from Elcodis.com electronic components distributor